

ABSTRACT OF THE DISCLOSURE

A cooling system for an electronic system housing a heat-generating component. The cooling system generally includes a heat sink having a length and a width. The heat sink is configured to dissipate heat generated by the heat-generating component and has a base and a plurality of fins attached to the base. The plurality of fins are spaced apart from one another to have a relatively low height to width aspect ratio in the spacing between the plurality of fins. In addition, the heat-generating component has a length and a width, and at least one of the length and the width of the heat sink is substantially larger than at least one of an associated length and width of the heat-generating component.